JOCMB83Ch-D8P/S Series

Soldering Temperature	T_{sol}	260	

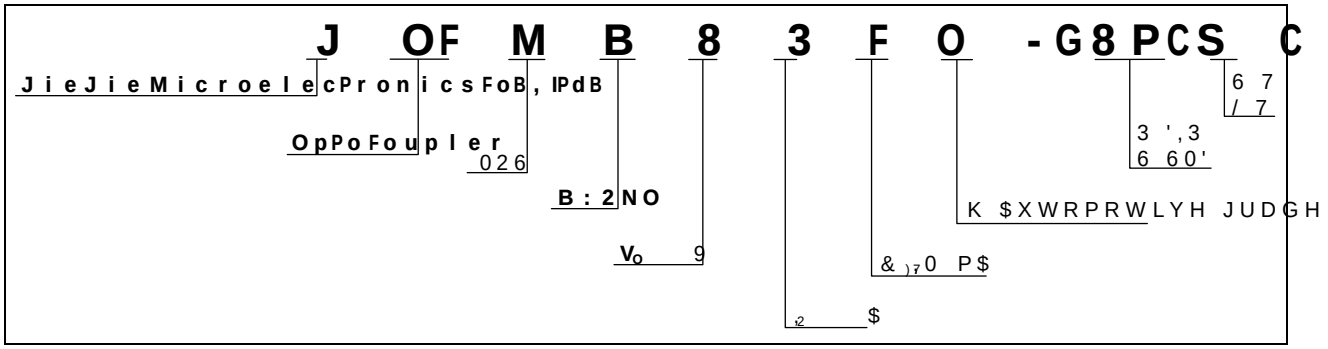
NOTE1 í ì ì … • ‰ íµì ò ,•Ì (ŒE ‹ µ v Ç

NOTE2 (} Œ í u] v µ š U Z X , X A ð ì • ò ì 9

ELECTRICAL CHARACTERISTICS (Temperature = 25 Á C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	I_F = 10mA	-	1.3	1.5	V
	Reverse Current	I_R	V_R = 6V	-	-	1	ε A
	Action Current	$I_{F(ON)}$	I_O = ϕ (MAX)	-	1.5	3	mA
	Reset Current	$I_{F(OFF)}$	I_O = ϕ (MAX)	0.4	0.8	-	mA
Output	On Resistance	R_{on}	I_F = 5mA I_O = Max. Within 1s on time	-	30	40	q
	Off State Lea k age Current	I_{Leak}	I_F = 0mA, V_O = Max.	-	-	1	ε A
	Output Capacitance	C_{OFF}	V_{OFF} = 0V, f_o = 1M H z	10	-	1000	pF
Switching Characteristics	Isolation Resistance	R_{ISO}	DC500V 40 ~ 60%R. H.	10^{12}	-	-	q
	Floating Capacitance	C_{IO}	V = 0, f = 1M H z	-	1.5	-	pF
	Turn On Time	t_{on}	I_F = 5mA, I_O = Max	-	0.18	0.5	ms
	Turn Off Time	t_{off}	I_F = 5mA, I_O = Max	-	0.2	1	ms

ORDERING INFORMATION



Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
DIP	p л Units к Tube	п л Tubes box Inner	p Inner box к Outer box Units
SMD	12 л л Units к Reel	2 Reels к box Inner	p Inner box к Outer box Units

MARKING

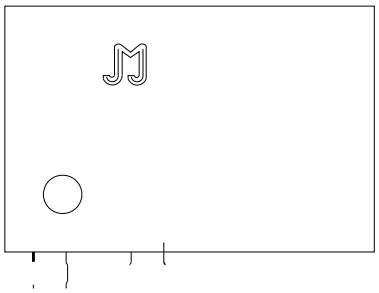


FIG.7: Turn On Time vs. Ambient Temperature

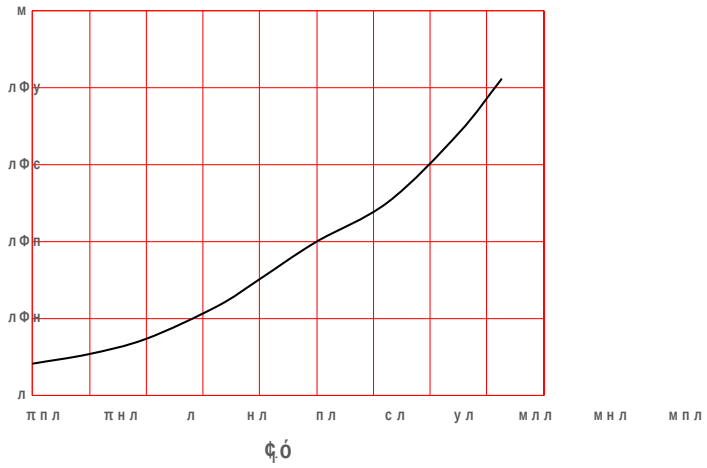


FIG.8: Turn Off Time vs. Ambient Temperature

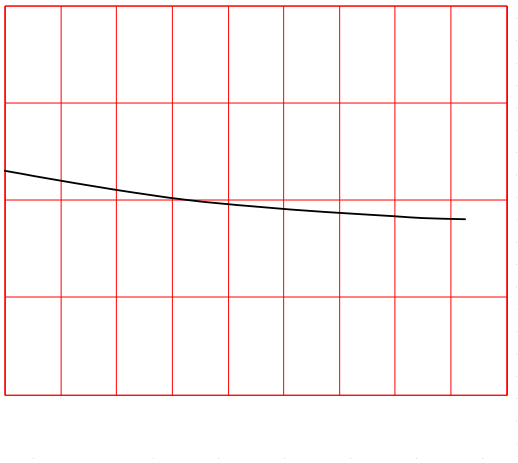


FIG.9: Turn On Time vs. LED Forward Current

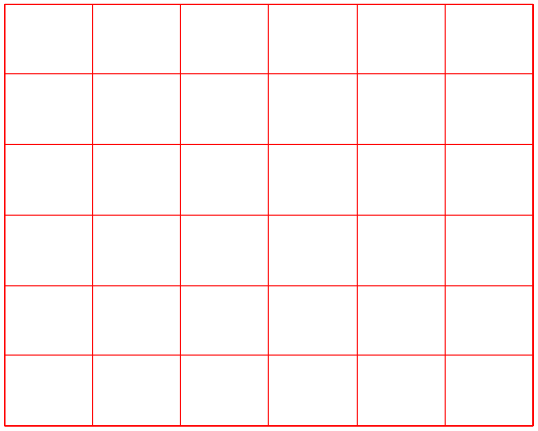
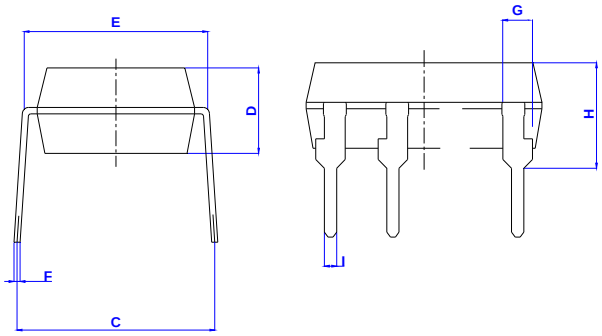


FIG.10: Turn Off Time vs. LED Forward Current

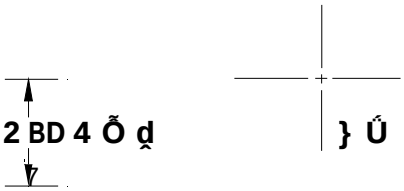
Package Dimension (Unit: mm)

Standard DIP Type:

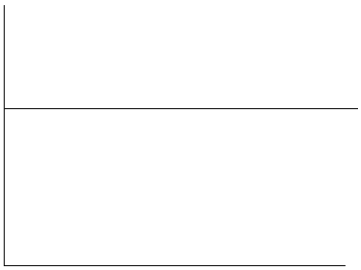


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J						

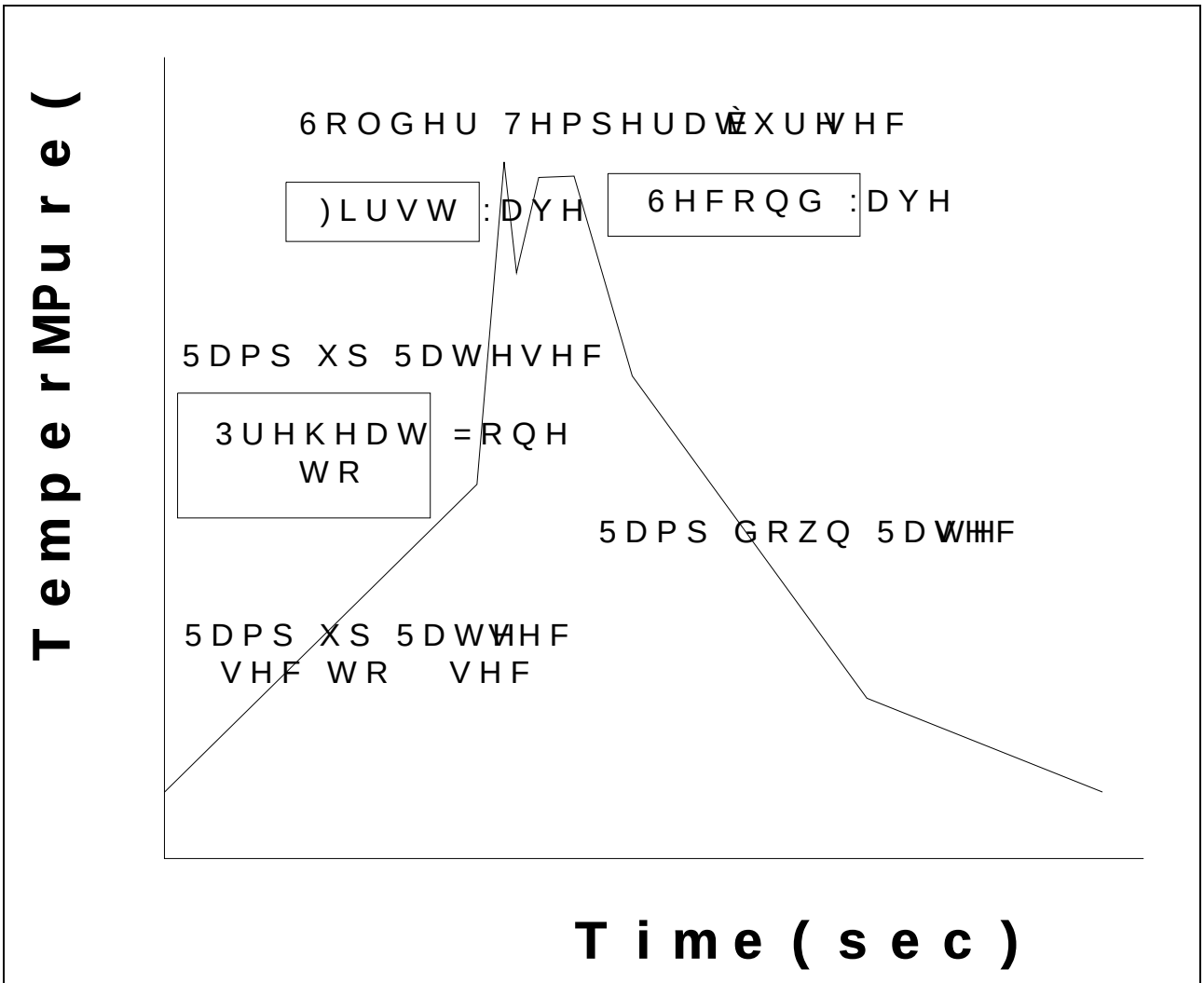
RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



REFLOW INFORMATION



WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temper MPure	360f0
6ROGHULQJ 7LPH	V PD[

Note:

1. Reflow soldering is recommended at the temperatures and time shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0 ~ 40ÁC ;

Recommend storage humidity: < 60% ;

MSL level: MSL 1

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co., Ltd. assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement.

Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information. This document supersedes and replaces all information previously supplied.

JieJie Microelectronics Co., Ltd. is a registered trademark of Jiangsu JieJie Microelectronics Co., Ltd.

Copyright © 2016 Jiangsu JieJie Microelectronics Co., Ltd. All rights reserved.